AP SERIES

Automated Stencil Printers
For Fine Pitch SMT Assembly

CLOSED LOOP CONTROL OF PRINT PARAMETERS

PROGRAMMABLE SQUEEGEE PRINT HEAD

SPC DATA COLLECTION SOFTWARE

MACHINE VISION AUTO–ALIGNMENT

AUTOMATIC STENCIL WIPER WITH SOLVENT DISPENSER

FULLY PROGRAM-MABLE PASTE DISPENSING SYSTEM

MPM CORPORATION

Technology for Perfect Printing

- All conventional fiducials acceptable, including circles, squares, bow ties, and donuts, as well as standard component pads.
- 0.030" to 0.100" (.762mm to 2.54mm)

Accuracy: ± 0.001" (± .0254mm)
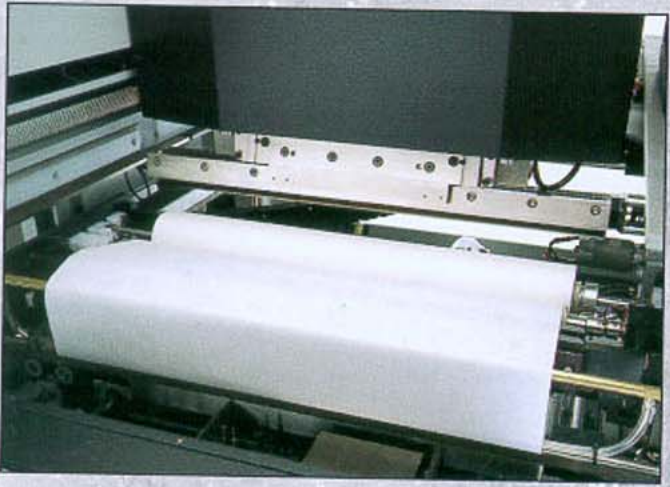**Repeatability:** ± 0.0005" (± 13 microns)

Automatic Stencil Wiper and Solvent Bar

Provides unassisted cleaning of the underside of the stencil at user-programmable intervals. The system allows variable wipe frequency, stroke speed, and wiping force, and accommodates various stencil sizes.

A solvent bar wetting system helps to remove any stubborn solder paste dried on the stencil. The system may be programmed for various combinations of wet and dry wiping.

Contaminants and paste removed from the stencil are trapped on easily replaced rolls of lint-free paper. This minimizes operator exposure to solder paste constituents.

SPECIFICATIONS:
Length of Wiping Blade:
10" to 19"
(254mm to 483mm)
Stroke Distance:
Programmable from 2"
(50mm) to 16" (406mm)
Solvent Type: A variety of non-CFC types available

Board Handling System

In-line system features automatic track width and speed controls for exceptional flexibility. A sliding vacuum nest with moveable magnetic support pins or blocks makes setup faster and easier. Double-sided boards are easily accommodated.

MPM's Board Handling System is available with fixed front track or optional fixed rear track. The system is compatible with all major board loading and placement equipment.